

L Number	Hits	Search Text	DB	Time stamp
-	28022	etchant or "etching gas"	USPAT; US-PGPUB	2002/12/17 18:10
-	145	(adsorb\$3 or adsorption or condens\$3 or condensation) with (etchant or "etching gas")	USPAT; US-PGPUB	2002/12/17 21:18
-	994349	water	USPAT; US-PGPUB	2002/12/17 21:18
-	21966	ozone and water	USPAT; US-PGPUB	2002/12/17 21:18
-	10405	(adsorb\$3 or adsorption or condens\$3 or condensation) and (ozone and water)	USPAT; US-PGPUB	2002/12/17 21:19
-	215	(etchant or "etching gas") and ((adsorb\$3 or adsorption or condens\$3 or condensation) and (ozone and water))	USPAT; US-PGPUB	2002/12/17 21:19
-	553830	semiconductor or "integrated circuit" or silicon	USPAT; US-PGPUB	2002/12/17 21:20
-	3533	((adsorb\$3 or adsorption or condens\$3 or condensation) and (ozone and water)) and (semiconductor or "integrated circuit" or silicon)	USPAT; US-PGPUB	2002/12/17 21:21
-	200	(adsorb\$3 or adsorption or condens\$3 or condensation) with ozone with water	USPAT; US-PGPUB	2002/12/17 21:21
-	15	(US-6337277-\$ or US-6099945-\$ or US-6024888-\$ or US-5935454-\$ or US-5500079-\$ or US-5354416-\$ or US-5087323-\$ or US-5030319-\$ or US-6299696-\$).did. or (US-20020177323-\$ or US-20020121502-\$ or US-20020038681-\$ or US-20010006849-\$ or US-20020134409-\$ or US-20020122753-\$).did.	USPAT; US-PGPUB	2002/12/18 12:25
-	490771	wafer or substrate	USPAT; US-PGPUB	2002/12/18 12:26
-	700153	cool\$3	USPAT; US-PGPUB	2002/12/18 12:26
-	22000	(wafer or substrate) with cool\$3	USPAT; US-PGPUB	2002/12/18 12:27
-	29628	ozone	USPAT; US-PGPUB	2002/12/18 12:27
-	828	((wafer or substrate) with cool\$3) and ozone	USPAT; US-PGPUB	2002/12/18 12:27
-	347653	@ad>20000523 @rlad>20000523	USPAT; US-PGPUB	2002/12/18 12:28
-	649	((wafer or substrate) with cool\$3) and ozone) not (@ad>20000523 @rlad>20000523)	USPAT; US-PGPUB	2002/12/18 12:28
-	1021500	water or steam	USPAT; US-PGPUB	2002/12/18 12:29
-	486	(((((wafer or substrate) with cool\$3) and ozone) not (@ad>20000523 @rlad>20000523)) and (water or steam)	USPAT; US-PGPUB	2002/12/18 12:29
-	392087	adsorb\$3 or adsorption or condens\$3 or condensation	USPAT; US-PGPUB	2002/12/18 12:30
-	289	(((((wafer or substrate) with cool\$3) and ozone) not (@ad>20000523 @rlad>20000523)) and (water or steam)) and (adsorb\$3 or adsorption or condens\$3 or condensation)	USPAT; US-PGPUB	2002/12/18 12:30
-	52	(semiconductor or "integrated circuit" or silicon) and ((adsorb\$3 or adsorption or condens\$3 or condensation) with ozone with water)	USPAT; US-PGPUB	2002/12/18 15:18
-	288	(((((wafer or substrate) with cool\$3) and ozone) not (@ad>20000523 @rlad>20000523)) and (water or steam)) and (adsorb\$3 or adsorption or condens\$3 or condensation)) not ((semiconductor or "integrated circuit" or silicon) and ((adsorb\$3 or adsorption or condens\$3 or condensation) with ozone with water))	USPAT; US-PGPUB	2002/12/18 12:31
-	35	(semiconductor or "integrated circuit" or silicon) and ((adsorb\$3 or adsorption or condens\$3 or condensation) and ozone and water)	EPO; JPO; DERWENT; IBM_TDB	2002/12/18 15:19

-	12	(semiconductor or "integrated circuit" or silicon) and ((adsorb\$3 or adsorption or condens\$3 or condensation) with ozone with water)	EPO; JPO; DERWENT; IBM_TDB	2002/12/18 15:22
-	23	((semiconductor or "integrated circuit" or silicon) and ((adsorb\$3 or adsorption or condens\$3 or condensation) and ozone and water)) not ((semiconductor or "integrated circuit" or silicon) and ((adsorb\$3 or adsorption or condens\$3 or condensation) with ozone with water))	EPO; JPO; DERWENT; IBM_TDB	2002/12/18 15:22
-	71	(US-6337277-\$ or US-6099945-\$ or US-6024888-\$ or US-5935454-\$ or US-5500079-\$ or US-5354416-\$ or US-5087323-\$ or US-5030319-\$ or US-6299696-\$ or US-6432845-\$ or US-6429493-\$ or US-6403498-\$ or US-6368891-\$ or US-6358830-\$ or US-6350685-\$ or US-6340435-\$ or US-6284205-\$ or US-6281141-\$ or US-6246105-\$ or US-6245659-\$ or US-6239041-\$ or US-6238511-\$ or US-6232156-\$ or US-6194304-\$ or US-6184068-\$ or US-6144097-\$).did. or (US-6143081-\$ or US-6107182-\$ or US-5967156-\$ or US-5962194-\$ or US-5953634-\$ or US-5925577-\$ or US-5923962-\$ or US-5904770-\$ or US-5843833-\$ or US-5840600-\$ or US-5714306-\$ or US-5643826-\$ or US-5078832-\$ or US-4911103-\$ or US-4910043-\$ or US-4906328-\$ or US-4891488-\$ or US-4886570-\$ or US-4877757-\$ or US-4875989-\$ or US-4863558-\$ or US-4857132-\$ or US-4855160-\$ or US-4844773-\$ or US-4842687-\$ or US-4842676-\$ or US-4836905-\$).did. or (US-4832779-\$ or US-4832777-\$ or US-4830705-\$ or US-4830700-\$ or US-4822450-\$ or US-4818327-\$ or US-4818326-\$ or US-4778532-\$).did. or (US-20020177323-\$ or US-20020121502-\$ or US-20020038681-\$ or US-20010006849-\$ or US-20020134409-\$ or US-20020122753-\$).did. or (JP-2001276758-\$ or US-20020050279-\$ or US-20020020436-\$ or WO-200137329-\$).did.	USPAT; US-PGPUB; DERWENT	2002/12/18 17:38
-	1	("6240933").PN.	USPAT; US-PGPUB	2002/12/18 17:38